

bq26150 Evaluation Software

The bq26150 provides a method to authenticate battery packs, ensuring that only packs manufactured by authorized sub-contractors are used in the end application. The bq26150 uses a unique 96-bit device key and a device-specific 16-bit CRC to provide security. The device key, CRC polynomial seed, and CRC polynomial coefficients are stored securely in each bq26150 device, allowing the host to authenticate each pack.

The purpose of the evaluation software is to demonstrate the functionality of the bq26150. The bq26150 test board can be used stand alone or with a second HDQ device.

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1 Kits Contents

1. bq26150, HPA116 board
2. CD-ROM including Windows® Operating System software and support documentation

2 bq26150 Based Circuit Module

The bq26150EVM based circuit module is an example circuit for authentication of a single cell Li-Ion battery pack. There are two separate circuits on the EVM module. One is the active bq26150 authenticating circuitry; the other is the logic and power control to program the on-chip One Time Programmable (OTP) memory. In a typical application, only the active authenticating circuitry is required. The OTP programming circuitry would be required in a test setup to configure the bq26150 for the application by programming the OTP.

Contacts on the circuit module provide direct connection to the cell (J3-1, J2-3), the serial communications port (J3-2). A second HDQ device connects at (J4-2, J4-1).

Table 1. Test Points

TEST POINT	SIGNAL NAME	DESCRIPTION
J2-1	SUPPLY	High voltage for OTP programming
J2-2	PROG	Input for timing of OTP programming
J2-3	VSS	System ground
J3-1	PACK+	Cell positive/pack positive
J3-2	HDQ	Single wire HDQ line
J4-1	VSS	System ground
J4-2	HDQP	Connection for second HDQ device

4 Circuit Module Physical Layouts

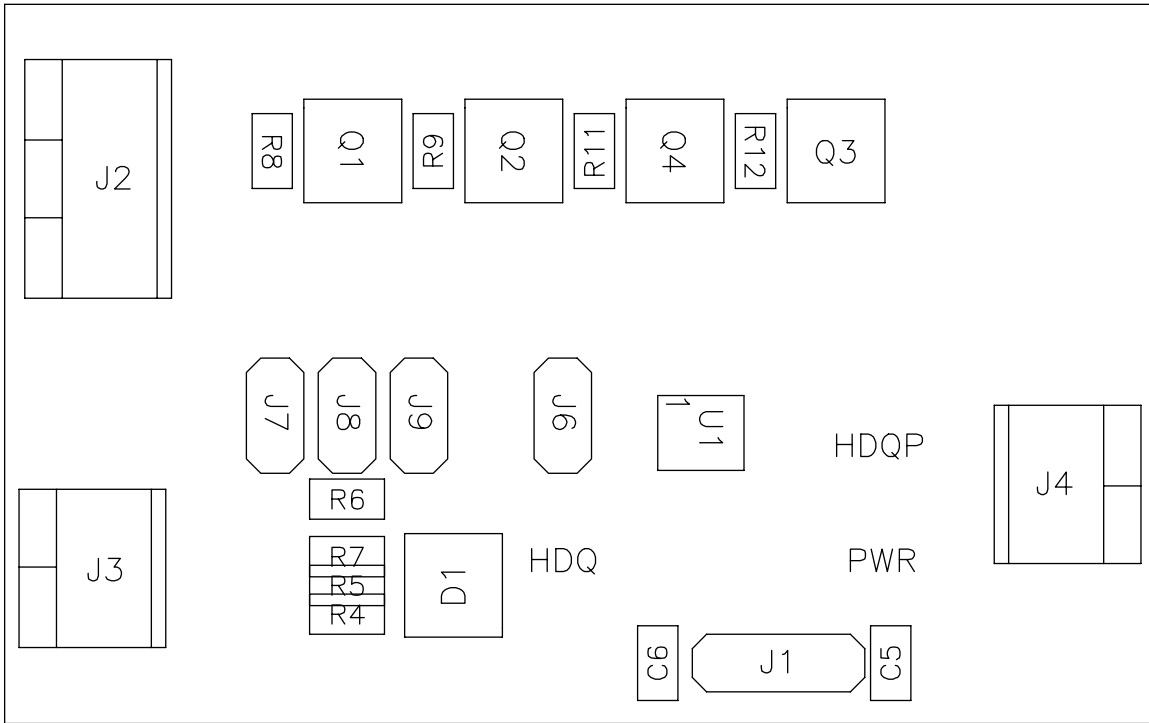


Figure 2. Topside Assembly

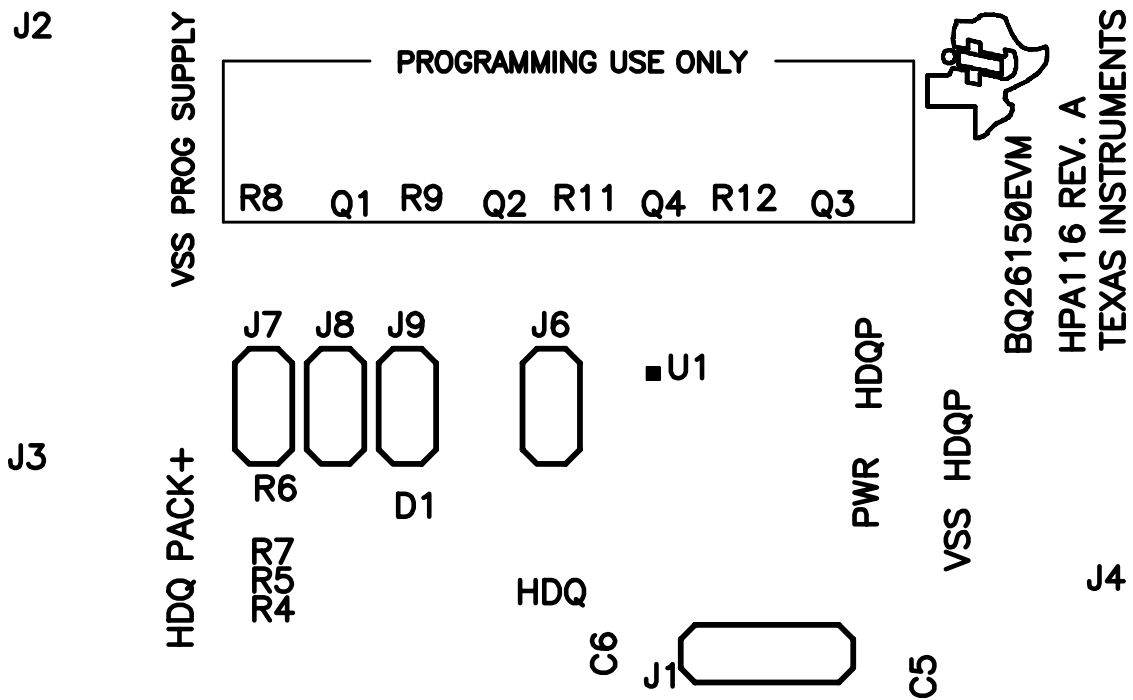


Figure 3. Silkscreen

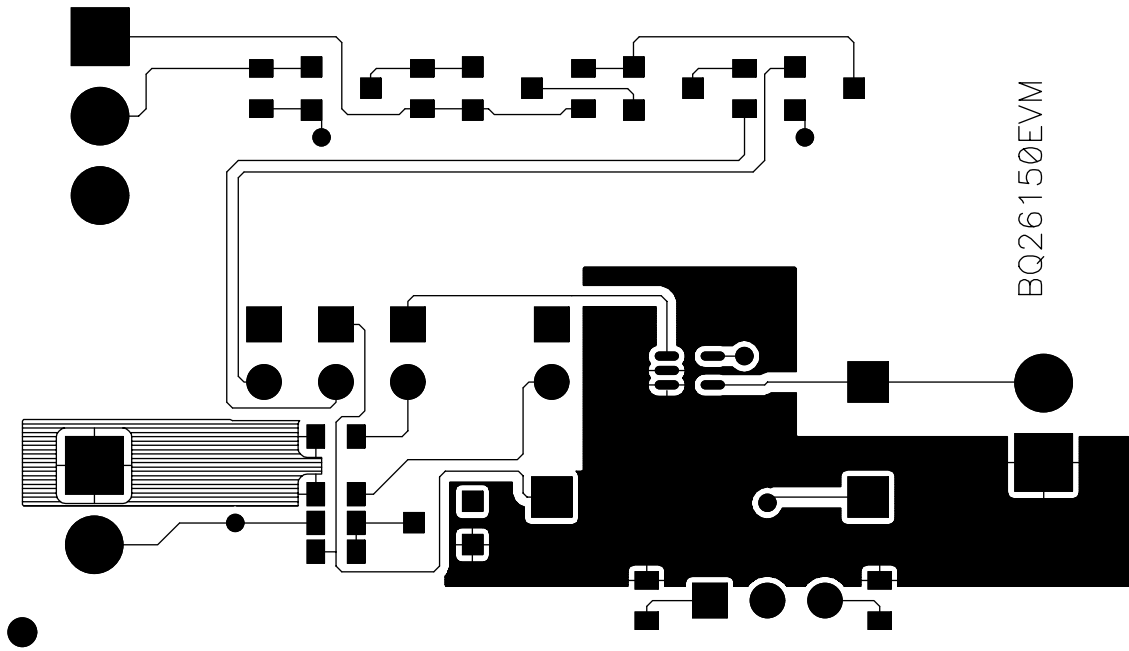


Figure 4. Top Layer

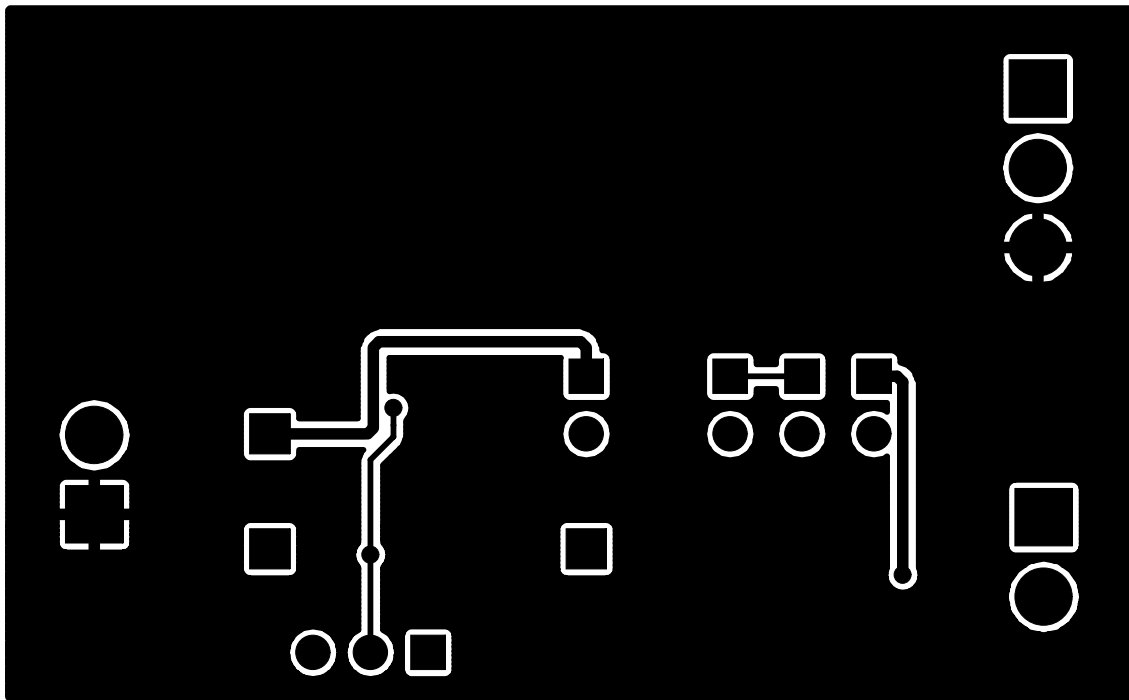


Figure 5. Bottom Layer

5 bq26150 Circuit Module List of Materials

Table 2 contains the list of materials required for the bq26150EVM circuit module.

Table 2. List of Materials

REF DES	QTY	DESCRIPTION	MFR	PART NUMBER
C5	1	Capacitor, Ceramic, 0.1-uF, 16-V, [X7R]	muRata	Std
C6	1	Capacitor, Ceramic, 0.01-uF, 16-V, [X7R]	muRata	Std
D1	1	Diode, Zener, 8.2-V, 350-mW	Diodes, Inc.	BZX84C8V2
J1	1	Header, 3-pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN
J2	1	Terminal Block, 3-pin, 6-A, 3.5mm	OST	ED1515
J3, J4	2	Terminal Block, 2-pin, 6-A, 3.5mm	OST	ED1514
J6, J7, J8, J9	4	Header, 2-pin, 100mil spacing, (36-pin strip)	Sullins	PTC36SAAN
Q1, Q3	2	MOSFET, N-ch, 60-V, 115-mA, 1.2-Ohms	Vishay-Liteon	2N7002DICT
Q2, Q4	2	MOSFET, Pch, -12V, -3.4A, 50 milliohm	IR	IRLML6401
R11	1	Resistor, Chip, 250-Ohms, 1/16-W	Std	Std
R12	1	Resistor, Chip, 1k-Ohms, 1/16-W	Std	Std
R4, R5	2	Resistor, Chip, 100-Ohms, 1/16-W	Std	Std
R6, R7	2	Resistor, Chip, 5.1k-Ohms, 1/16-W	Std	Std
R8	1	Resistor, Chip, 100k-Ohms, 1/16-W	Std	Std
R9	1	Resistor, Chip, 10k-Ohms, 1/16-W	Std	Std
N/A	5	Shunt, 100mil, Black	3M	929950-00
U1	1	IC, Battery Pack Security and Authentication	TI	BQ26150DCK

6 EVM Hardware and Software Setup

6.1 Software Installation

This section describes how to install the bq26150EVM PC software and how to connect the different components of the EVM.

The following steps install the bq26150 evaluation software:

1. Insert CD ROM into a CD ROM drive.
2. Select the CD ROM drive using **My Computer** on the desktop or the **File Manager** or **Explorer** utility.
3. Open the ReadMeFirst.txt file, and follow the instructions to install the USB drivers for EV2300.
4. When USB installation completes, double-click on the Setup.exe icon.
5. The setup program installs an application group in the programs menu.

6.2 Hardware Connection

The EVM work environment includes three hardware components:

- bq26150EVM circuit module
- PC interface board (EV2300 – available separately)
- Host PC

A second HDQ device can be connected with the bq26150, permitting communication between the second HDQ device and the EV2300.

The following steps configure the hardware for interface to the PC:

1. Connect colored wires that are included with EV2300 to bq26150EVM using Table 1 as a guide.
2. Connect the connector with colored wires to the HDQ connector that is on EV2300. HDQ connection is located on the top right of EV2300.
3. Connect the PC USB cable to the EV2300 and the PC USB port.

The bq26150EVM is now set up for operation.

Table 3. Wire Connection

bq26150 EVM	Wire Color
HDQ	Brown
VSS	Black
PROG	White

To program the OTP of bq26150 a 7 V pulse must be generated on the HDQ line. The HPA116 board has an additional circuit included that permits generating this pulse when using a Power Supply set to 8.5 V and the VOUT output of the EV2300. The evaluation software controls this pulse for OTP programming.

When programming of OTP is expected the 8.5 V supply must be connected to the HPA116 board at the SUPPLY input of the board. Ensure that the ground of the power supply is connected to VSS of the board.

There are five jumpers that can be connected. Depending on what functionality of the system is going to be used then the jumpers should be connected in a specific configuration.

6.2.1 Normal Operation

Normal operation includes reading registers from bq26150, writing to RAM registers such as Random Challenge registers and Authentication Control register. If using the EV2300 to communicate with the bq26150 do not connect J9. This jumper is for using a pull-up resistor on the HDQ line. The EV2300 already provides a pull-up resistor that allows HDQ communication.

6.2.2 OTP Programming

To program OTP registers it is required to send a 7V pulse across the HDQ line after sending the appropriate write command. See datasheet for specific description of OTP programming requirements. When programming OTP registers is expected, the following must be ensured:

- Jumpers J7 and J8 are connected
- VOUT output of EV2300 is connected to PROG input of HPA116 board.
- Power supply set to 8.5V is connected across the SUPPLY and VSS inputs of HPA116 board. Supply must be on when mentioned jumpers are connected to allow valid HDQ communication.

7 Software Operation

Run the program from the **Start|Programs|Texas Instruments|bq26150 EVSW** menu sequence. If the EV2300 is not connected to a USB port, the program will display a USB error message and then display the initial REGISTERS data screen.

7.1 Evaluation Software Pages

This section describes the function of each page of the EVSW.

7.2 REGISTERS

Within this page is where all the authentication functions of bq26150 take place ([Figure 6](#)).

Sections Within the Registers Page

Polynomial Seed – This section is to read the encrypted Polynomial Seed and enter the plaintext Polynomial Seed values that are used to initialize the authentication CRC.

Polynomial Coefficients – This section is to read the encrypted Polynomial Coefficient and enter the plaintext Polynomial Coefficient values that define the CRC circuit used during authentication.

Device ID Registers – This section is to read the Encrypted Device ID and enter the Plaintext Device ID values.

Random Challenge – The 32 bit random challenge is generated and sent to the bq26150.

Authentication Control Register – This section determines if the system goes into continuous pass or one time pass mode. The POR bit can be read and cleared. The DONE bit gives status of authentication process. The AUTH bit initiates an authentication process. The continuous or one time pass modes can be initiated from this register. Once CPASS or OPASS have been set they may be canceled so that communication directly to the bq26150 is allowed by clicking on the CANCEL button shared by both features.

Reset bq26150 – Resets the IC by pulling HDQ line low for a determined time.

Authentication CRC by bq26150 – Reads the Authentication CRC registers from the bq26150.

Authentication CRC by Host – Calculates the CRC based on the decryption done by host and the random challenge.

Once a bq26150 has the Encrypted and Plaintext versions of the Polynomial and Device ID registers programmed in OTP as desired by the customer or Texas Instruments Inc representative then the user can go through the steps required to authenticate. The user can use these steps as a guide to how to develop later on system host firmware.

Steps to authenticate using Evaluation Software:

1. Select the Read command. This will read all encrypted version of Polynomial Seed, Polynomial Coefficients and Device ID registers.
2. The user must decrypt the values read in the previous step based on whatever cryptography scheme was used to obtain the cipher text versions of these registers.
3. Select the Generate command that is in the Random Challenge section.
4. Select the Send to bq26150 command. This will send the random challenge value obtained in the previous step of this sequence and write it into the Random Challenge registers of the bq26150.
5. Select the Authentication command (AUTH). This will instruct the bq26150 to calculate a CRC of the Plaintext Device ID (96 bit) and Random Challenge (32 bit) based on the Plaintext Polynomial Seed

and Plaintext Polynomial Coefficients.

6. If DONE at the Authentication Control register is set (red and bold) then a CRC has been calculated by the bq26150. Select the Read CRC command to get the values of the Authentication CRC Value registers.
7. Select the Calculate CRC command to have the host, in this case the PC determine the CRC value of the deciphered Device ID values and the Random Challenge registers based on the deciphered Polynomial values.
8. Compare the CRC read from the bq26150 and the CRC calculated by the PC to determine if authentication is successful.

Make variations to the steps described above to prove that only a correct combination of deciphered Polynomial Seed, Polynomial Coefficients and Device ID are needed so that authentication is successful.

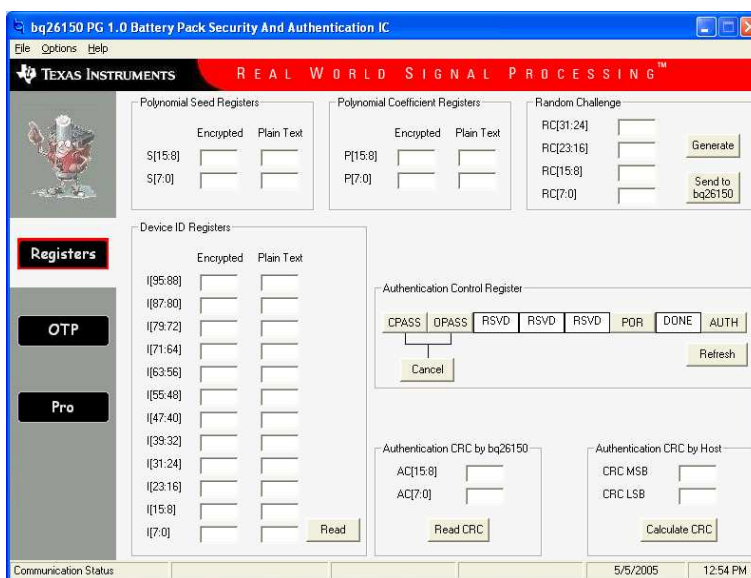


Figure 6. Registers Page

7.3 OTP

This page (Figure 7) allows the user to program the OTP with desired values. It requires that the hardware is setup as described in section 2.2.2 of this user's guide.

Sections Within the OTP Page

General Purpose Memory – The user can program any values to these registers.

Encrypted Registers – The encrypted version of the Polynomial Seed, Polynomial Coefficients and Device ID registers are programmed in this section. The values must be predetermined by the user by using any encryption scheme that it may see suitable. After a write attempt, the evaluation software reads back and displays the values of these registers.

Plaintext Registers – The plain-text version of the Polynomial Seed, Polynomial Coefficients and Device ID registers are programmed in this section. These values tend to be chosen by the user before encrypting them so that they can be used in the Encrypted versions. After a write attempt to the Plain-text registers the evaluation software displays 00.

OTP File Import – A file with extension .otp containing the OTP registers' values can be loaded to the text fields so that the values can be programmed to OTP. The evaluation software comes with an example OTP file.

Device Lock – These buttons write a value to nibbles of Device Lock register. When writing to a specific nibble of the Device Lock register certain OTP registers will be locked so that no further programming is allowed. After locking the device, writes to the Polynomial Seed, Polynomial Coefficients and Device ID are not allowed. See datasheet for details on Device Lock.

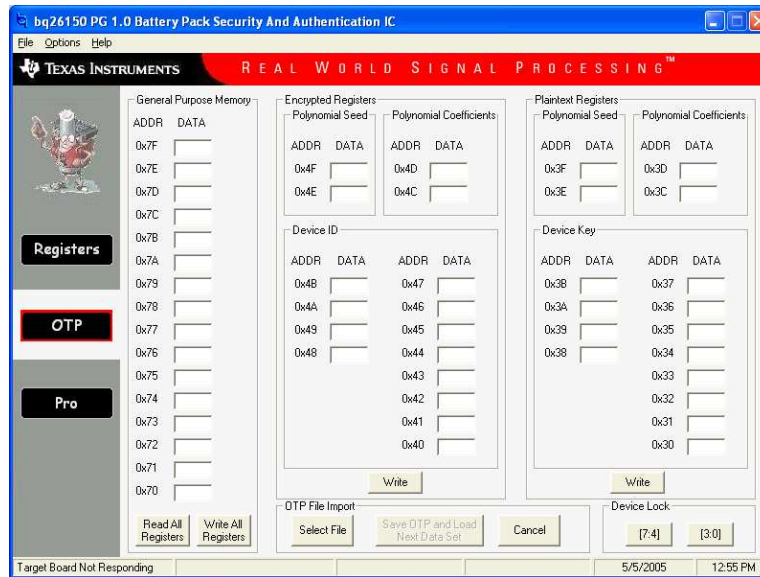


Figure 7. OTP Page

7.4 PRO

This page (Figure 8) allows the user to read from or write to the bq26150 when in normal operation or read from or write to a second HDQ device when in CPASS or OPASS mode.

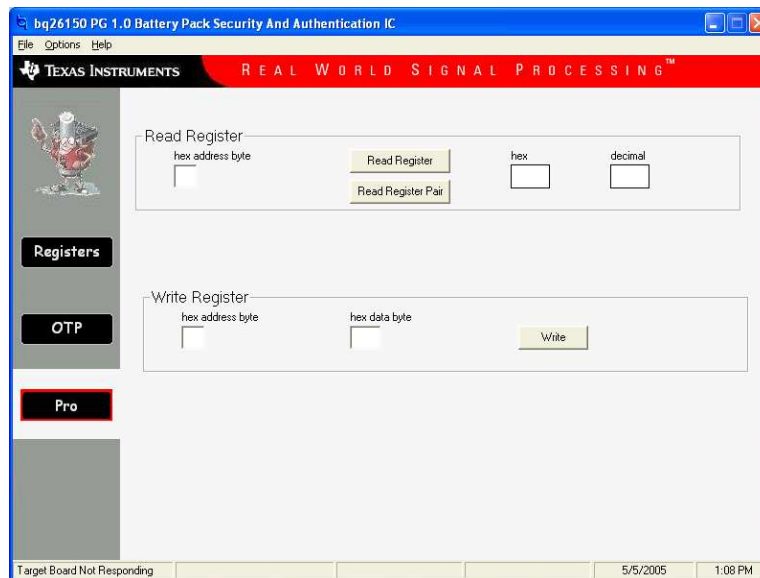


Figure 8. PRO Page

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